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Application Number 10/674,569 LANSMITTAL Filing Date September 29, 2003 **FORM** First Named Inventor Janakiraman, Karthik Art Unit 1763 **Examiner Name** ZERVIGON, RUDY ed for all correspondence after initial filing) Attorney Docket Number 016301-045510US Total Number of Pages in This Submission **ENCLOSURES** (Check all that apply) After Allowance Communication to TC Fee Transmittal Form Drawing(s) Appeal Communication to Board Fee Attached Licensing-related Papers of Appeals and Interferences Appeal Communication to TC Amendment/Reply Petition (Appeal Notice, Brief, Reply Brief) Petition to Convert to a After Final **Proprietary Information Provisional Application** Power of Attorney, Revocation Affidavits/declaration(s) Status Letter Change of Correspondence Address Other Enclosure(s) (please identify **Extension of Time Request** Terminal Disclaimer below): Return Postcard **Express Abandonment Request** Request for Refund Information Disclosure Statement CD, Number of CD(s) Landscape Table on CD The Commissioner is authorized to charge any additional fees to Deposit Remarks Certified Copy of Priority Account 20-1430. Document(s) Reply to Missing Parts/ Incomplete Application Reply to Missing Parts under 37 CFR 1.52 or 1.53 SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT Firm Name Townsend and Townsend and Crew LLP Signature Printed name Kent J. Tobin Date Reg. No. April 19, 2007 39,496

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Appeal Brief - Patents, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date shown below. Signature Typed or printed name Sharyl Brown Date April 19, 2007



PATENT

Attorney Docket No.: A6378C1/T45510 AMAT No.: 006378 USA P01/DSM/PMD/JPFEIFFER

TTC File No.: 016301-045510US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Karthik Janakiraman et al.

Application No.: 10/674,569

Filed: September 29, 2003

For: GAS DISTRIBUTION

SHOWERHEAD

Confirmation No. 3855

Examiner: Rudy Zervigon

Technology Center/Art Unit: 1763

APPELLANTS' BRIEF UNDER 37 CFR § 41.37

MAIL STOP APPEAL BRIEF - PATENTS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Applicants, in the above-captioned patent application, appeal the final rejection of claims 1 and 3-5. The claims on appeal have been finally rejected pursuant to MPEP § 706.06(a). Accordingly, this appeal is believed to be proper.

I. REAL PARTY IN INTEREST

The real party in interest for the above-identified application is APPLIED MATERIALS, INC., having its principal place of business at P.O. Box 450A, Santa Clara, California 95052. Assignment of the instant application to APPLIED MATERIALS, INC. is recorded in the U.S. Patent and Trademark Office on September 29, 2003 at Reel 014574/Frame 0777.

II. RELATED APPEALS AND INTERFERENCES

There are no appeals or interferences related to the present appeal.

III. STATUS OF CLAIMS

Claims 1 and 3-5 are pending.

Claim 1 was finally rejected as anticipated under 35 U.S.C. § 102(e), based upon the grounds set forth in the Office Action mailed October 4, 2006.

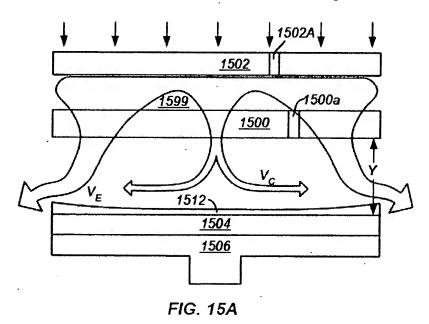
Claims 1 and 3-5 were finally rejected as obvious under 35 U.S.C. § 103(a), also based upon the grounds set forth in the Office Action mailed October 4, 2006.

IV. STATUS OF AMENDMENTS

Applicants filed a Response on July 17, 2006 in reply to the Office Action mailed April 17, 2006. A Final Office Action mailed October 4, 2006 indicated that the Response did not place the application in condition for allowance. A copy of the claims involved in the appeal are contained in the Appendix attached hereto.

V. SUMMARY OF CLAIMED SUBJECT MATTER

Embodiments in accordance with the present invention relate to a gas distribution face plate having characteristics promoting uniform deposition of material on a substrate. As depicted schematically in FIG. 15A (reproduced below), the inventors observed that gases flowed through conventional showerheads (1500) having orifices (1500a) of widths of about 0.029 inches (29 mils), could result in formation of a material layer (1512) of uneven thickness, owing to different velocities of the gas at the center (V_C) versus edge (V_E) of the substrate:



Accordingly, a new face plate design was proposed having orifices of narrower width of between about 0.010-0.018 inches (10-18 mils), in order to promote a uniform pressure drop across edge and center portions of the faceplate, and hence uniform gas velocities resulting in the deposition of a layer of uniform thickness. The results are shown in FIG. 16 (reproduced below):

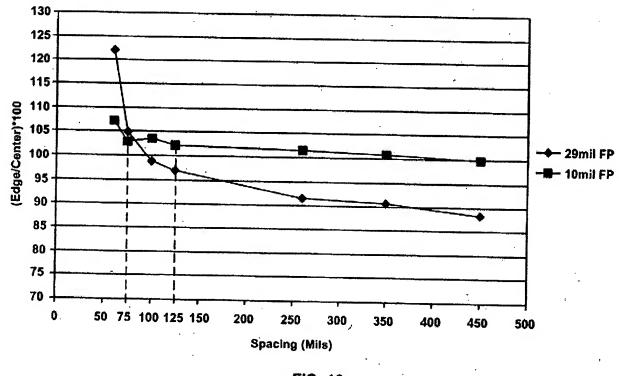


FIG. 16

FIG. 16 reveals that films formed by gas flows through the novel (**a**) faceplate (FP) having orifices of width of 10 mils (0.010"), exhibited superior uniformity as compared with films formed by gas flows through a conventional (**4**) faceplate (FP) having orifices of width of 29 mils (0.029"). In particular, the films deposited utilizing the novel faceplate exhibited less variation in thickness over a substantially wider range of faceplate-to-wafer spacings.

Moreover, FIG. 16 also shows a profound lack of predictability in the relationship between the two curves, particularly at narrow faceplate-to-wafer spacings. This unpredictability reflects the considerable time and effort required by the inventors to develop a faceplate having the desired characteristics.

Independent claim 1 accordingly recites as follows:

1. A gas distribution face plate comprising:

a face plate body having a thickness defining a number of inlet orifices having a width of between about 0.010" and 0.018" and a depth, at least one parameter selected from the number, the width, and the depth configured to create a uniform pressure drop of between about 0.8 and 1 Torr across edge and center regions of the faceplate as gas is flowed through the inlet orifices, whereby a thickness of material deposited at an edge of a wafer varies by 3% or less from a thickness of material deposited at a center of the wafer, when the wafer is separated from the face plate by a gap of between about 75 and 450 mils.

Remaining claims 3-5 depend from claim 1 and recite various other face plate parameters

3. The face plate of claim 1 wherein the number comprises between about 2000 and 17500 orifices.

* * *

4. The faceplate of claim 3 wherein the number comprises about 10000 and the face plate is configured to process a wafer having a diameter of about 300 mm.

* * *

5. The faceplate of claim 3 wherein the number comprises about 5000 and the face plate is configured to process a wafer having a diameter of about 200 mm.

VI. GROUNDS OF REJECTION TO BE REVIEWED ON APPEAL

- A. Claim 1 stands rejected as anticipated under 35 U.S.C. § 102(e) by U.S. Patent No. 6,454,860 to Metzner et al. ("the Metzner Patent").
- B. Claims 1 and 3-5 stand rejected as obvious under 35 U.S.C. § 103(a) in view of Japanese Patent Application No. 4[1992]-154116 to Toki et al. ("the Toki Application").

VII. ARGUMENT

A. Claim 1 is not anticipated by the Metzner Patent

As a threshold matter, claim 1 stands rejected as anticipated, and not merely obvious, in view of the Metzner Patent:

[t]he distinction between rejections based on 35 U.S.C. 102 and those based on 35 U.S.C. 103 should be kept in mind. Under the former, the claim is anticipated by the reference. No question of obviousness is present. In other words, for anticipation under 35 U.S.C. 102, the reference must teach every aspect of the

claimed invention either explicitly or impliedly. Any feature not directly taught must be inherently present. (Emphasis added; MPEP 706.02)

Here, the Metzner Patent contains no teaching, implicit or even implied, regarding each element of claim 1. For example, the Metzner Patent consistently teaches a showerhead structure exhibiting orifices having widths equivalent to, or even larger than, those of the conventional showerheads distinguished by the present invention:

Inlet **291** is axially symmetric to aperture centerline **267** and could be cylindrically shaped with a <u>diameter 247 of 0.028 inches</u>. (Emphasis added; col. 10, lines 8-10)

* * *

inlet diameter 247 is less than outlet diameter 288 or inlet diameter 247 could be about one-third of outlet diameter 288 such as when a representative aperture 249 has an <u>inlet diameter 247 of 0.028 inches</u> (Emphasis added; col. 10, lines 34-38)

* * *

Utilizing the ratios above, representative dimensions for each of a plurality of apertures 249 in a representative showerhead 240 fabricated from aluminum having a thickness of about 0.5 inches are: an <u>inlet diameter 247 of about 0.028 inches</u> (Emphasis added; col. 10, lines 52-56)

* * *

Inlet **291** is axially symmetric to aperture centerline **267** and could be cylindrically shaped with <u>a diameter **247** of 0.110 inches</u>. (Emphasis added; col. 11, lines 4-5)

* * *

Given the above ratios, dimensions for each of a plurality of representative apertures 238 in an aluminum showerhead 240 having a thickness of about 0.4 inches are: an inlet diameter 247 of about 0.110 inches (Emphasis added; col. 12, lines 12-15)

There is absolutely no teaching or suggestion in the Metzner Patent, regarding use of inlet orifices of the widths recited by claim 1.

In the most recent office action, the Examiner asserted that the Metzner Patent disclosed the claimed range at col. 9 line 38 and at col. 9 lines 53-64. Careful review of the Metzner Patent, however, fails to reveal any disclosure of the claimed orifice widths, in the cited passages or anywhere else for that matter.

Specifically, at col. 9 line 38, the Metzner Patent describes attaching the shower head and blocker plate to the lid using fasteners. A col. 9, lines 53-64, the Metzner Patent generally introduces Figures 6 and 8. Neither passage teaches orifices having a particular width.

The Examiner may have intended to refer to col. 10 of the Metzner Patent. For example, ccl. 10, line 38 recites an orifice having a width of 28mils, as does col. 10, line 56. Such an orifice width is, however, characteristic of the conventional face plate that is recognized by, and specifically differentiated from, the present invention.

The remainder of the Metzner Patent teaches orifices having an even greater width (110mil.) (See col. 11, line 5, and col. 12, line 15). Such a large orifice width can hardly be understood to suggest the much smaller range of orifice widths claimed by Applicants.

Because the Metzner Patent fails to teach, explicitly or even impliedly, each and every element of the pending claims, it is respectfully asserted that the anticipation claim rejection has been overcome. Accordingly, for at least these reasons, continued maintenance of the anticipation claim rejections is improper, and these claim rejections should be withdrawn.

B. Claims 1 and 3-5 are not Obvious in View of the Toki Application

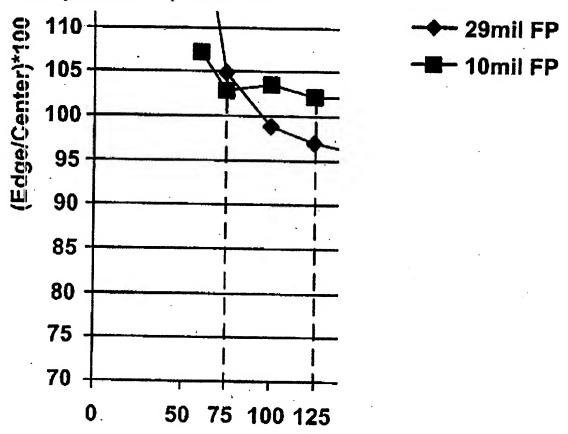
In order to establish a prima facie case of obviousness, "the prior art reference (or references when combined) must teach or suggest all of the claim limitations." (MPEP 2143).

Here, a complete English language translation of the Toki Application has been submitted for review by the Examiner. After reviewing this document, the Examiner openly concedes that the Toki Application fails to provide any teaching regarding many of the features of the claimed gas distribution shower head:

Toki does not teach the wafer separation distance of 75 to 450 mils and the exact pressure drop of 0.8 and 1Torr range across the face plate body 21. Toki further does not teach his face plate body 21 with the number of orifices (25,26; Figure 1) between 2000 and 17,500 orifices and where said orifices have widths between 0.010 and 0.018 inches as claimed. (Emphasis added; Office Action Mailed October 4, 2006, page 4, lines 5-8)

Nevertheless, in maintaining final rejection of the claims, the Examiner simply asserts that it would have been obvious to one of ordinary skill to optimize the dimensions and number of inlet orifices to optimize the claimed film thickness variation.

Applicants vigorously dispute this conclusion. An enlarged portion of Figure 16 of the instant specification is reproduced below:



This portion of FIG. 16 of the instant application amply evidences the highly unpredictable correlation between orifice size and showerhead performance. In particular, a reduction in orifice width by approximately one-third (from 29mil to 10mil), does not result in a corresponding change in the edge-center variation of thickness of a deposited layer. Instead, FIG. 16 indicates that the curves are non-linear with respect to one another other, with this non-linearity increasing at closer face plate-to-wafer spacings.

This profound lack of predictability between orifice width and face plate performance demonstrated in FIG. 16, runs directly counter to any reasonable conclusion of obviousness. Rather than merely representing ordinary efforts at optimization, development of the claimed embodiments are the result of difficult and time-consuming experimentation involving a highly

complex and unpredictable chemical process. The art relied upon by the Examiner does not support a conclusion of obviousness, and the claim rejections should be withdrawn.

VIII. CONCLUSION

In view of the foregoing arguments distinguishing claims 1 and 3-5 over the art of record, Applicants respectfully submit that the claims are in condition for allowance, and respectfully request that the rejection of these claims be reversed.

Respectfully submitted,

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IX. CLAIMS APPENDIX

- 1. (Previously Presented) A gas distribution face plate comprising:
- a face plate body having a thickness defining a number of inlet orifices having a width of between about 0.010" and 0.018" and a depth, at least one parameter selected from the number, the width, and the depth configured to create a uniform pressure drop of between about 0.8 and 1 Torr across edge and center regions of the faceplate as gas is flowed through the inlet orifices, whereby a thickness of material deposited at an edge of a wafer varies by 3% or less from a thickness of material deposited at a center of the wafer, when the wafer is separated from the face plate by a gap of between about 75 and 450 mils.
 - 2. (Canceled)
- 3. (Original) The face plate of claim 1 wherein the number comprises between about 2000 and 17500 orifices.
- 4. (Original) The faceplate of claim 3 wherein the number comprises about 10000 and the face plate is configured to process a wafer having a diameter of about 300 mm.
- 5. (Original) The faceplate of claim 3 wherein the number comprises about 5000 and the face plate is configured to process a wafer having a diameter of about 200 mm.
 - 6-18. (Canceled).

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X. EVIDENCE APPENDIX

None.

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XI. RELATED PROCEEDINGS APPENDIX

None.